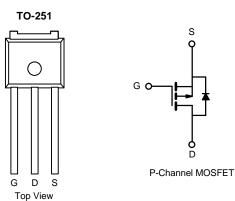


# AP4435GJ-VB Datasheet P-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	$R_{DS(on)}\left(\Omega\right)$	I <sub>D</sub> (A) <sup>d</sup>	Q <sub>g</sub> (Typ.)		
- 30	0.018 at V <sub>GS</sub> = - 10 V	- 40	13 nC		
	0.022 at V <sub>GS</sub> = - 4.5 V	- 35	13110		



# **FEATURES**

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET<sup>®</sup> Power MOSFET
- 100 % R<sub>g</sub> Tested

# **APPLICATIONS**

- · Load Switch
- Battery Switch





<b>ABSOLUTE MAXIMUM RATINGS</b> T	A = 25 °C, unless other	erwise noted		
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V <sub>DS</sub>	- 30	V	
Gate-Source Voltage	V <sub>GS</sub>	± 20	V	
	T <sub>C</sub> = 25 °C		- 40	
Continuous Proin Current /T 150 °C)	T <sub>C</sub> = 70 °C		- 35	
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>A</sub> = 25 °C	I <sub>D</sub>	- 30.0 <sup>a, b</sup>	
	T <sub>A</sub> = 70 °C		- 28 <sup>a, b</sup>	Α
Pulsed Drain Current	I <sub>DM</sub>	- 150		
Continuous Course Dunin Die de Course	T <sub>C</sub> = 25 °C		- 3.5	
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	I <sub>S</sub>	- 2.1 <sup>a, b</sup>	
	T <sub>C</sub> = 25 °C		40	
Manifestore Device District	T <sub>C</sub> = 70 °C		32	10/
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	2.5 <sup>a, b</sup>	W
	T <sub>A</sub> = 70 °C		1.6 <sup>a, b</sup>	
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient <sup>a, c</sup>	t ≤ 10 s	R <sub>thJA</sub>	40	50	°C/W	
Maximum Junction-to-Foot	Steady State	R <sub>thJF</sub>	24	30	C/VV	

#### Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 10 s.
- c. Maximum under Steady State conditions is 95 °C/W.
- d. Based on  $T_C = 25$  °C.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 30			V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	In = - 250 HA		- 31		mV/°C
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$			4.5		
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1.0		- 2.5	V
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
Zoro Coto Voltago Droin Current	I <sub>DSS</sub>	V <sub>DS</sub> = - 30 V, V <sub>GS</sub> = 0 V			- 1	μA
Zero Gate Voltage Drain Current		V <sub>DS</sub> = - 30 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C		- 5		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \le -5 \text{ V}, V_{GS} = -10 \text{ V}$	- 20			Α
Danie O	D	V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 7.0 A				Ω
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 5.6 A		0.022		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 7.0 A		18		S
Dynamic <sup>b</sup>						
Input Capacitance	C <sub>iss</sub>			1455		pF
Output Capacitance	C <sub>oss</sub>	$V_{DS} = -15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		180		
Reverse Transfer Capacitance	C <sub>rss</sub>			145		
Total Cata Charge	$Q_g$ $V_{DS} = -15 \text{ V}, V_{GS} = -10 \text{ V}, I_D = -7.0 \text{ A}$	$V_{DS} = -15 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -7.0 \text{ A}$		25	38	
Total Gate Charge			13	20		
Gate-Source Charge	$Q_{gs}$	$V_{DS} = -15 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -7.0 \text{ A}$		3.5		- nC
Gate-Drain Charge	$Q_{gd}$			5.5		
Gate Resistance	R <sub>g</sub>	f = 1 MHz	0.4	2.0	4.0	Ω
Turn-On Delay Time	t <sub>d(on)</sub>			10	20	
Rise Time	t <sub>r</sub>	,   55		13	20	
Turn-Off DelayTime	t <sub>d(off)</sub>	$I_D \cong -5.6 \text{ A}, V_{GEN} = -10 \text{ V}, R_g = 1 \Omega$		23	35	
Fall Time	t <sub>f</sub>			9	18	
Turn-On Delay Time	t <sub>d(on)</sub>			38	57	ns
Rise Time	$t_r$ $V_{DD} = -15 \text{ V}, R_L = 2.7 \Omega$			89	134	1
Turn-Off DelayTime	t <sub>d(off)</sub>	$I_D \cong -5.6 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$		22	33	1
Fall Time	t <sub>f</sub>			11	17	
Drain-Source Body Diode Characteris	tics					
Continous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			- 6.5	Α
Pulse Diode Forward Current	I <sub>SM</sub>				- 30	_ ^
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = - 5.6 A, V <sub>GS</sub> = 0 V		- 0.71	- 1.2	V
Body Diode Reverse Recovery Time	- 05 0			22	33	ns
Body Diode Reverse Recovery Charge	$Q_{rr}$	L = 56 A dl/dt = 100 A/up T = 25 °C		17	26	nC
Reverse Recovery Fall Time	t <sub>a</sub>	$I_F = -5.6 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		13		ns
Reverse Recovery Rise Time	t <sub>b</sub>			9		

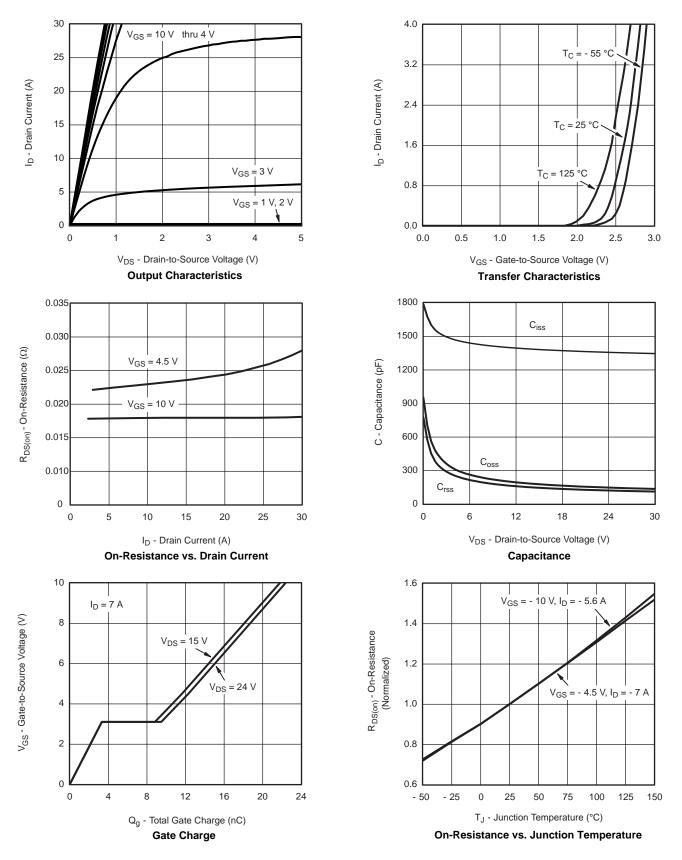
#### Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

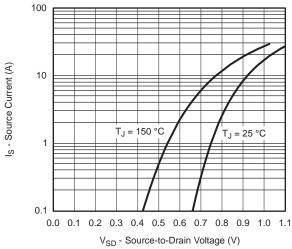
a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$ 

b. Guaranteed by design, not subject to production testing.

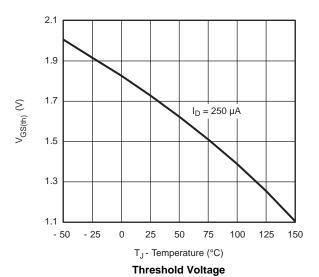


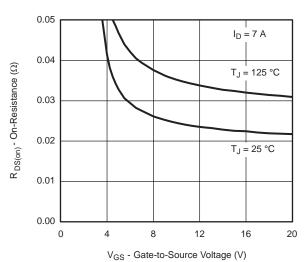




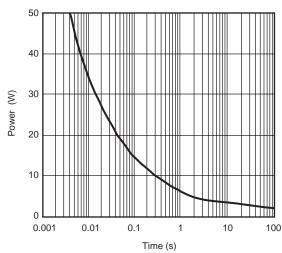


#### Source-Drain Diode Forward Voltage

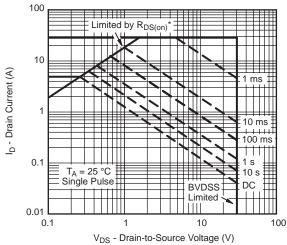




On-Resistance vs. Gate-to-Source Voltage



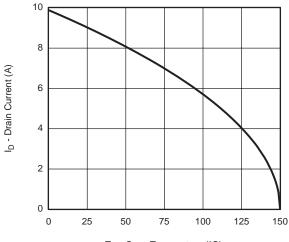
Single Pulse Power, Junction-to-Ambient



\* V<sub>GS</sub> > minimum V<sub>GS</sub> at which R<sub>DS(on)</sub> is specified

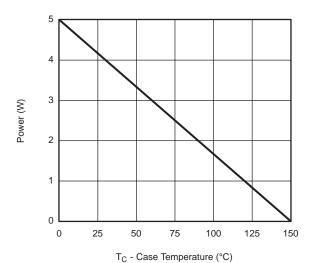
Safe Operating Area



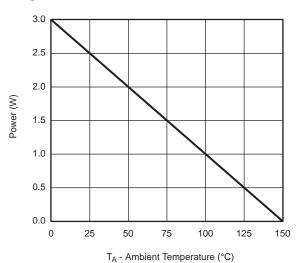


T<sub>C</sub> - Case Temperature (°C)

## **Current Derating\***



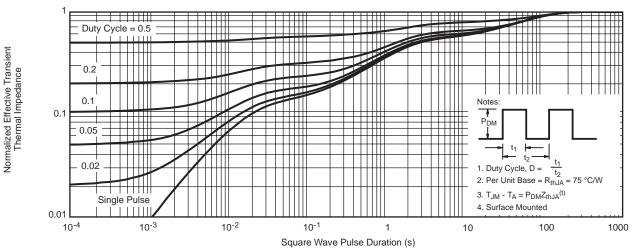
Power, Junction-to-Foot



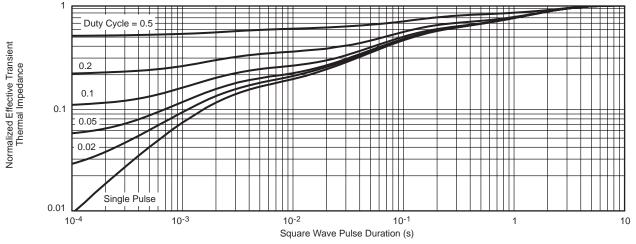
Power Derating, Junction-to-Ambient

<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





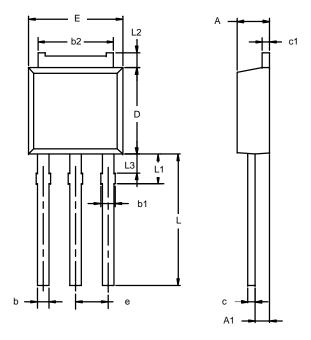
Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot



# TO-251AA (DPAK)



Note: Dimension L3 is for reference only.

	MILLIM	IETERS	INC	HES	
Dim	Min	Max	Min	Max	
Α	2.21	2.38	0.087	0.094	
<b>A</b> 1	0.89	1.14	0.035	0.045	
b	0.71	0.89	0.028	0.035	
b1	0.76	1.14	0.030	0.045	
b2	5.23	5.43	0.206	0.214	
С	0.46	0.58	0.018	0.023	
с1	0.46	0.58	0.018	0.023	
D	5.97	6.22	0.235	0.245	
Е	6.48	6.73	0.255	0.265	
е	2.28 BSC		0.090 BSC		
L	3.89	9.53	0.153	0.375	
L1	1.91	2.28	0.075	0.090	
L2	0.89	1.27	0.035	0.050	
L3	1.15	1.52	0.045	0.060	
ECN: S-03946—Rev. E, 09-Jul-01 DWG: 5346					



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